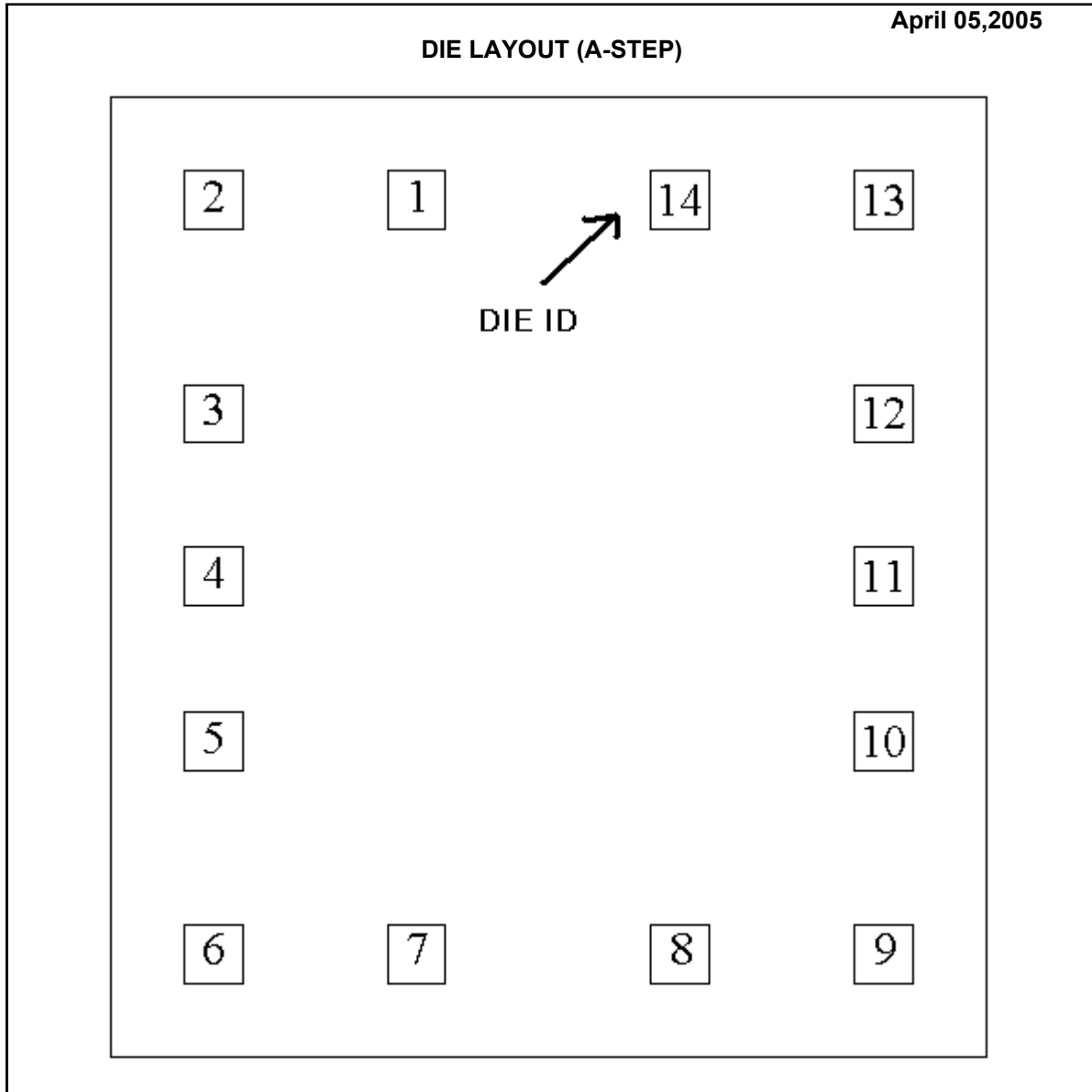


**LMH6644 MDC MWC**  
**LOW POWER, 130MHZ, 75MA RAIL-TO-RAIL OUTPUT AMPLIFIER**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	LMH6644A	Bond Pad Opening Size (min)	90μm x 90μm
Die Step	A	Bond Pad Metalization	Al_ 0.5%Cu
Physical Attributes		Passivation	PECVDOX+NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1349μm x 1478μm 53.1mils x 58.2mils	Back Side Connection	Floating
Thickness	406μm Nominal		
Min Pitch	251μm Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
OUT A	1	-203	580	90	x	90
-IN A	2	-516	580	90	x	90
+IN A	3	-516	252	90	x	90
V+	4	-516	1	90	x	90
+IN B	5	-516	-253	90	x	90
-IN B	6	-516	-580	90	x	90
OUT B	7	-203	-580	90	x	90
OUT C	8	203	-580	90	x	90
-IN C	9	516	-580	90	x	90
+IN C	10	516	-253	90	x	90
V-	11	516	1	90	x	90
+IN D	12	516	252	90	x	90
-IN D	13	516	580	90	x	90
OUT D	14	203	580	90	x	90

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